

M5M5278P, J-20, -25, -35, -25L, -35L M5M5278FP-25, -35, -25L, -35L

262144-BIT (32768-WORD BY 8-BIT) CMOS STATIC RAM

DESCRIPTION

The M5M5278 is a family of 32768-word by 8-bit static RAMs, fabricated with the high-performance CMOS silicon-gate MOS process and designed for high-speed application. These devices operate on a single 5V supply, and are directly TTL compatible. They include a power-down feature as well.

FEATURES

- Fast access time M5M5278P, J-20 20ns(max)
M5M5278P, J, FP-25, -25L 25ns(max)
M5M5278P, J, FP-35, -35L 35ns(max)
- Low power dissipation Active 300mW(typ)
Stand by(-20, -25, -35) 5mW(typ)
Stand by(-25L, -35L) 50μW(typ)
- Power down by \bar{S}
- Single 5V power supply
- Fully static operation
- Requires neither external clock nor refreshing
- All inputs and outputs are directly TTL compatible
- Easy memory expansion by chipselect(\bar{S})input
- Output enable (\bar{OE}) prevents data contention in the I/O bus
- All address inputs are changeable with each other

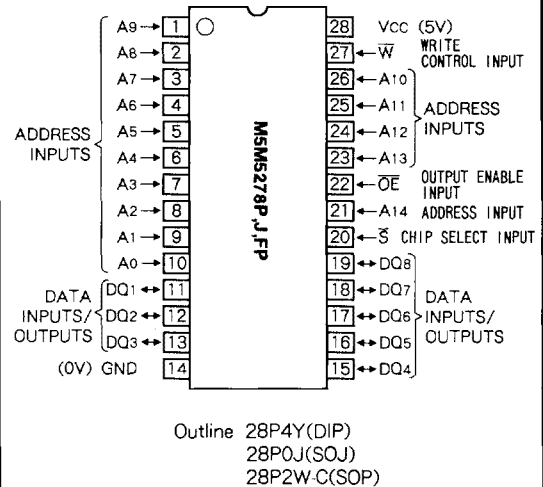
APPLICATION

High-speed memory systems

FUNCTION

A write operation is executed during the \bar{S} low, and \bar{W} low overlap time. In this period, address signals must be stable. When \bar{W} is low, the DQ terminal is maintained in the high impedance state.

PIN CONFIGURATION (TOP VIEW)

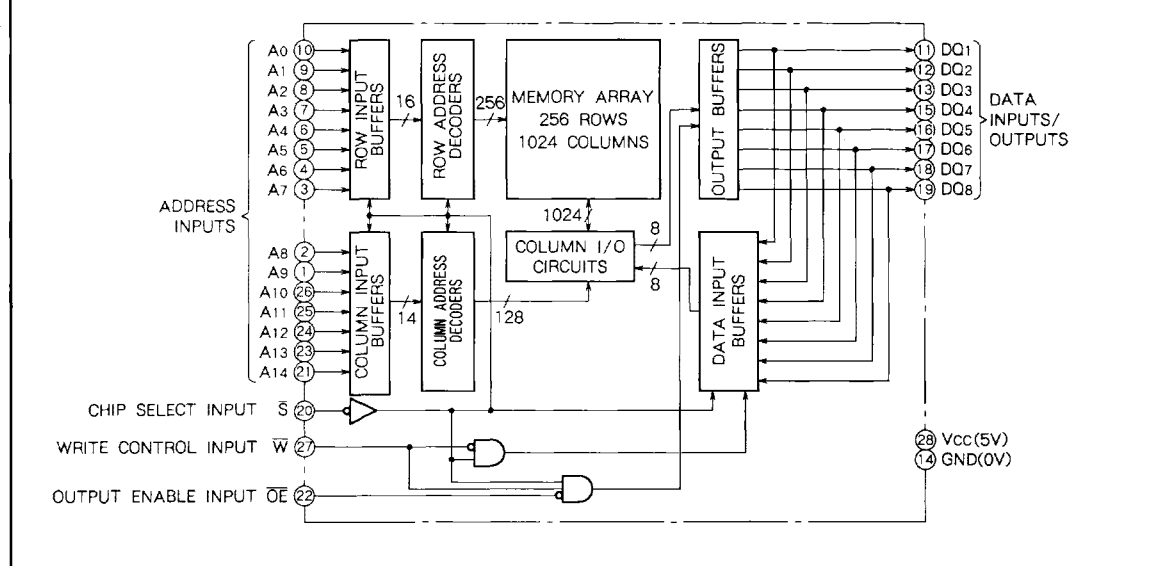


In a read operation, after setting \bar{W} to high, \bar{S} to low, and \bar{OE} to low if the address signals are stable, the data is available at the DQ terminal.

When \bar{S} is high, the chip is in the non-selectable state, disabling both reading and writing. In this case the output is in the floating (high-impedance) state, useful for OR-ties with other devices.

Signal \bar{S} controls the power-down feature. When \bar{S} goes high, power dissipation is reduced extremely. The access time from \bar{S} is equivalent to the address access time.

BLOCK DIAGRAM



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MODE SELECTION

S	W	OE	Mode	Data input/output	I _{cc}
H	X	X	Non selection	High-impedance	Stand by
L	L	X	Write	D _{in}	Active
L	H	L	Read	D _{out}	Active
L	H	H		High-impedance	Active

H : V_{IH} L : V_{IL} X : V_{IH} or V_{IL}

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage	With respect to GND	- 3.5* ~7	V
V _i	Input voltage		- 3.5* ~7	V
V _o	Output voltage		- 3.5* ~7	V
P _d	Maximum power dissipation		1	W
T _{opr}	Operation temperature		0~70	°C
T _{stg(bias)}	Storage temperature(bias)		- 10~85	°C
T _{stg}	Storage temperature		- 65~150	°C

* Pulse width ≤ 20ns, In case of DC : - 0.5V

DC ELECTRICAL CHARACTERISTICS (T_a = 0~70 °C, V_{cc} = 5V ± 10%, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{IH}	High-level input voltage		2.2		V _{cc} +0.3	V
V _{IL}	Low-level input voltage		- 0.5*		0.8	V
V _{OH}	High-level output voltage	I _{OH} = - 4mA	2.4			V
V _{OL}	Low-level output voltage	I _{OL} = 8mA			0.4	V
I _i	Input current	V _i = 0~V _{cc}			2	μA
I _{oz}	Off-state output current	V _{i(S)} = V _{IH} , V _o = 0~V _{cc}			10	μA
I _{cc1}	Supply current from V _{cc}	V _{i(S)} = V _{IL} Output open	AC(20ns cycle)		140	mA
			AC(25ns cycle)		130	
			AC(35ns cycle)		120	
			DC	60	90	
I _{cc2}	Stand by current	V _{i(S)} = V _{IH}	AC(20,25,35ns cycle)		40	mA
			Other V _i ≥ V _{IH} or ≤ V _{IL}		30	
I _{cc3}	Stand by current	V _{i(S)} = V _{cc} - 0.2V Other V _i ≤ 0.2V or V _i ≥ V _{cc} - 0.2V	-20, -25, -35	1	10	mA
			-25L, -35L	10	100	

Note 1. Current flow into an IC is positive, out is negative.
* - 0.3V in case of AC (Pulse width ≤ 20ns)

CAPACITANCE

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _i	Input capacitance	V _i = GND, V _i = 25mVrms, f = 1MHz			5	pF
C _o	Output capacitance	V _o = GND, V _o = 25mVrms, f = 1MHz			7	pF

AC ELECTRICAL CHARACTERISTICS (T_a = 0~70 °C, V_{cc} = 5V ± 10%, unless otherwise noted)

(1) MEASUREMENT CONDITIONS

Input pulse levels V_{IH} = 3V, V_{IL} = 0V
 Input rise and fall time 3ns
 Input timing reference levels V_{IH} = 2.4V, V_{IL} = 0.6V
 Output timing reference levels V_{OH} = 2.0V, V_{OL} = 0.8V
 Output loads Fig.1, Fig.2

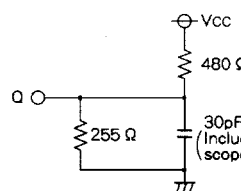


Fig.1 Output load

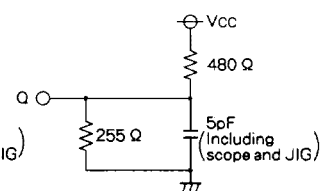


Fig.2 Output load for ten, tdis

M5M5278P, J-20, -25, -35, -25L, -35L M5M5278FP-25, -35, -25L, -35L

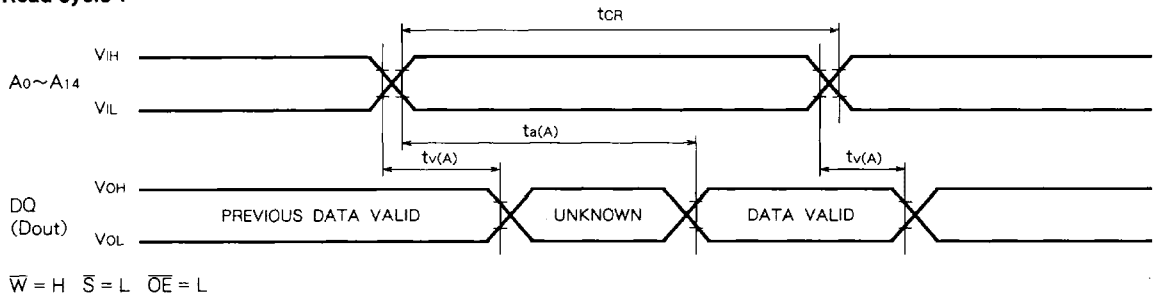
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(2) READ CYCLE

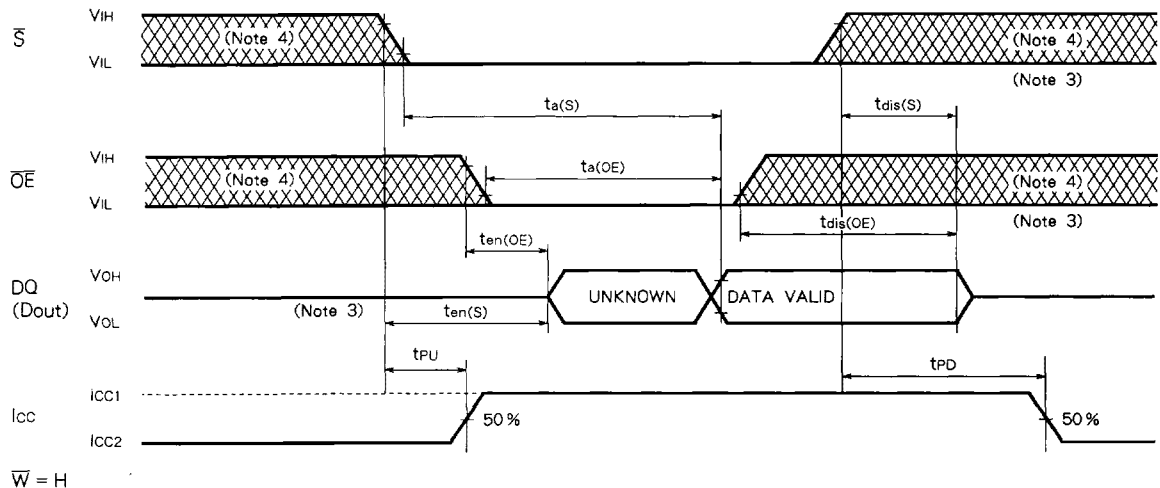
Symbol	Parameter	Limits						Unit
		M5M5278-20		M5M5278-25, -25L		M5M5278-35, -35L		
		Min	Max	Min	Max	Min	Max	
tCR	Read cycle time	20		25		35		ns
ta(A)	Address access time		20		25		35	ns
ta(S)	Chip select access time		20		25		35	ns
ta(OE)	Output enable access time		10		12		15	ns
tv(A)	Data valid time after address change	3		5		5		ns
ten(S)	Chip selection to output active(\bar{S})	3		5		5		ns
ten(OE)	Chip selection to output active(\bar{OE})	0		0		0		ns
tdis(S)	Output disable time from(\bar{S})	0	8	0	10	0	10	ns
tdis(OE)	Output disable time from(\bar{OE})	0	8	0	10	0	10	ns
tPU	Power-up time after chip selection	0		0		0		ns
tPD	Power-down time after chip selection		20		25		35	ns

(3) TIMING DIAGRAMS FOR READ CYCLE

Read cycle 1



Read cycle 2 (Note 2)



- Note 2. Addresses valid prior to or coincident with \bar{S} transition low.
 Note 3. Transition is measured $\pm 500mV$ from steady state voltage with specified loading in Figure 2.
 Note 4. Hatching indicates the state is don't care.

M5M5278P,J-20,-25,-35,-25L,-35L
M5M5278FP-25,-35,-25L,-35L

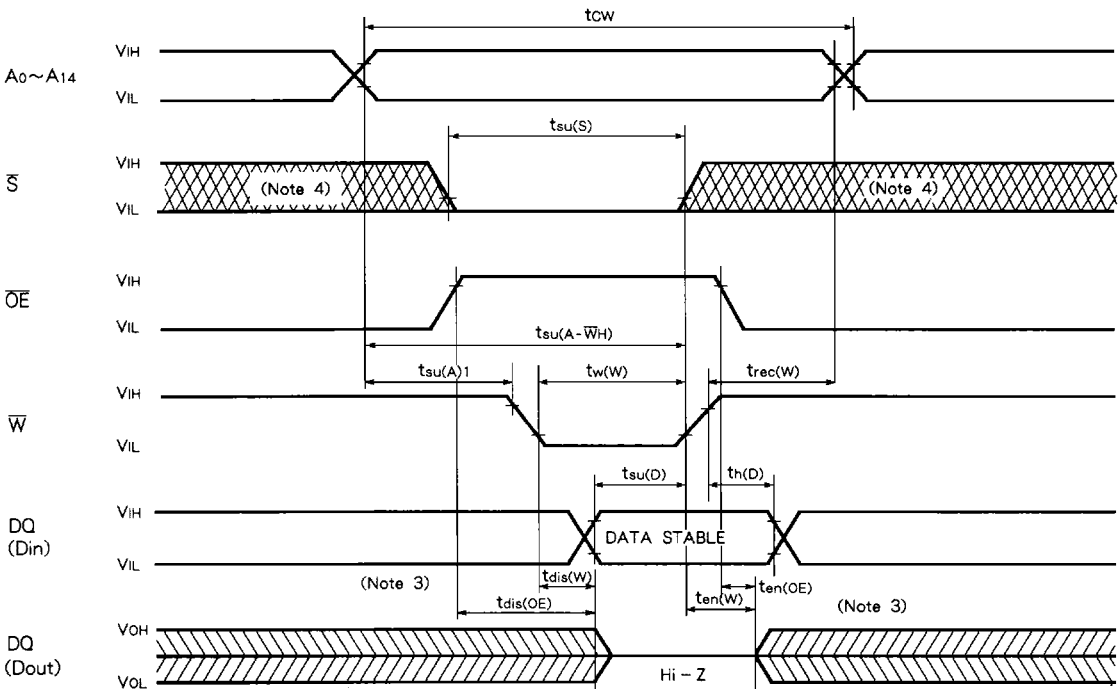
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(4) WRITE CYCLE

Symbol	Parameter	Limits						Unit
		M5M5278-20		M5M5278-25,-25L		M5M5278-35,-35L		
		Min	Max	Min	Max	Min	Max	
t _{cw}	Write cycle time	20		25		35		ns
t _{su(S)}	Chip select setup time	15		20		30		ns
t _{su(A)1}	Address setup time(\bar{W})	0		0		0		ns
t _{su(A)2}	Address setup time(\bar{S})	0		0		0		ns
t _{w(W)}	Write pulse width	15		20		25		ns
t _{rec(W)}	Write recovery time	0		0		0		ns
t _{su(D)}	Data setup time	8		10		15		ns
t _{h(D)}	Data hold time	0		0		0		ns
t _{dis(W)}	Output disable time from \bar{W}	0	8	0	10	0	10	ns
t _{dis(OE)}	Output disable time from \bar{OE}	0	8	0	10	0	10	ns
t _{en(W)}	Output enable time from \bar{W}	0		0		0		ns
t _{en(OE)}	Output enable time from \bar{OE}	0		0		0		ns
t _{su(A-\bar{W}H)}	Address to \bar{W} high	15		20		30		ns

(5) TIMING DIAGRAMS FOR WRITE CYCLE

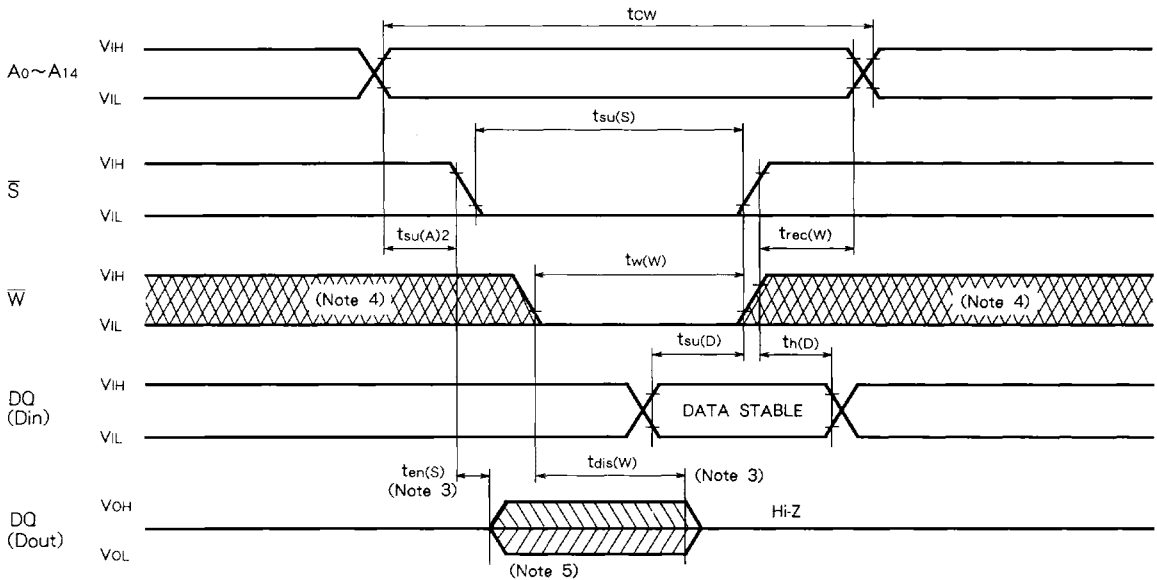
Write cycle 1 (\bar{W} control mode)



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Write cycle 2 (\bar{S} control mode)



Note 5. When the falling edge of \bar{W} is simultaneous or prior to the falling edge of \bar{S} , the output is maintained in the high impedance.

POWER DOWN CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{CC(PD)}$	Power down supply voltage		2			V
$V_{I(\bar{S})}$	Chip select input voltage	$V_{I(\bar{S})} \geq V_{CC} - 0.2\text{V}$	$V_{CC} - 0.2$			V
$t_{su(PD)}$	Power down setup time	$V_i \geq V_{CC} - 0.2\text{V}$ or $0\text{V} \leq V_i \leq 0.2\text{V}$	0			ns
$t_{rec(PD)}$	Power down recovery time		-25L	25		ns
			-35L	35		
$I_{CC(PD)}$	Power down supply current	$V_{CC} = 3.0\text{V}$			50	μA
		$V_{CC} = 5.5\text{V}$			100	

Note 6. This is only M5M5278P, J, FP-25L, -35L.

TIMING WAVEFORM FOR POWER DOWN

